1. Part No. Expression

W 2012 F 500 - R D - 10

- (a) (b) (c) (d) (e) (f) (g
- (a) Series Code

(e) Packaging Code

(b) Dimension Code

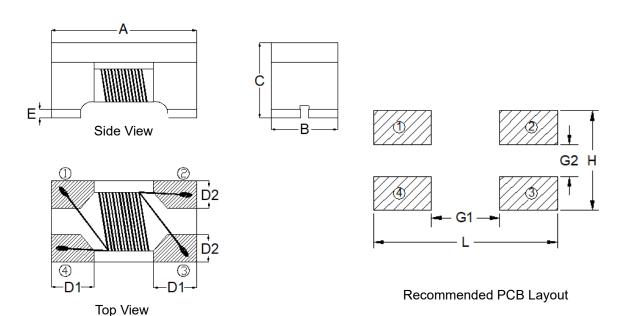
(f) Current Code

(c) Material Code

(g Internal Code

(d) Impedance Code

2. Configuration & Dimensions (Unit: mm)

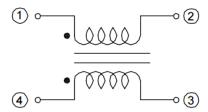


Note: The above PCB layout reference only.

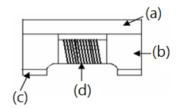
А	В	С	D1	D2
2.00±0.20	1.20±0.20	1.20±0.20	0.55±0.10	0.46±0.10
Е	L	G1	G2	Н
0.15±0.10	2.60 Ref	1.20 Ref	0.50 Ref	1.20 Ref



3. Schematic



4. Material List



- (a) Upper Plate
- (b) Core
- (c) Termination
- (d) Wire

5. General Specifications

- (a) Operating Temp.: -40°C to +125°C (including self-temperature rise)
- (b) Irms: Based on temperature rise ΔT 20°C Max at rated current < 1A and ΔT 40°CMax at rated current ≥ 1A
- (c) Storage Condition (Component in its packaging)

i) Temperature: Less than 40°C

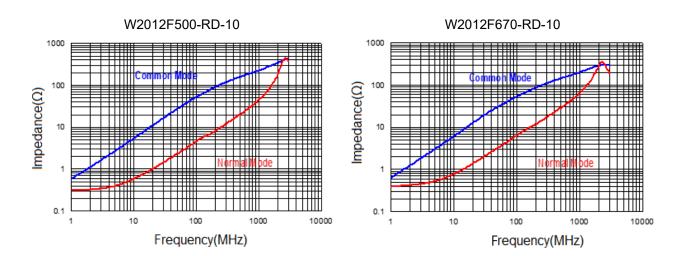
ii) Humidity: Less than 60% RH

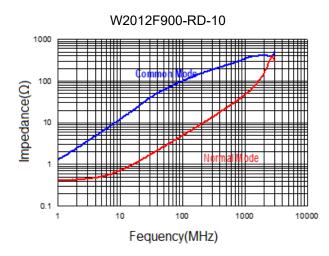
6. Electrical Characteristics

Part Number	Impedance (Ω) ±25%	Test Frequency (MHz)	DCR (Ω) Max	Rated Current (mA)	Rated Voltage (Vdc)	Withstand Voltage (Vdc)	IR (MΩ) Min
W2012F500-RD-10	50	100	0.25	400	50	125	10
W2012F670-RD-10	67	100	0.30	400	50	125	10
W2012F900-RD-10	90	100	0.30	400	50	125	10

7. Characteristics Curve

7-1. Impedance versus Frequency

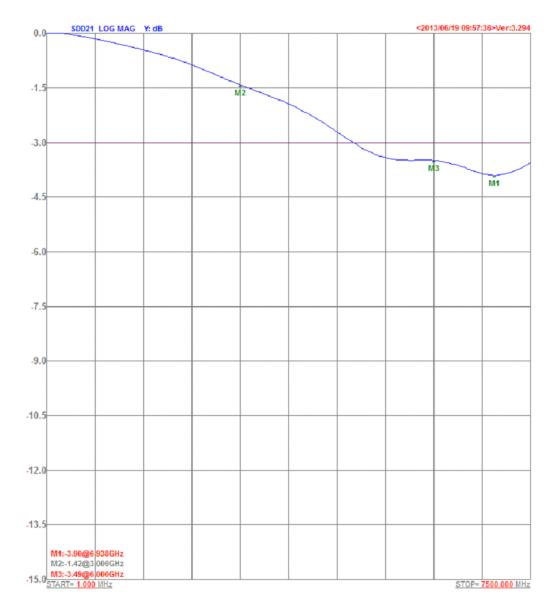




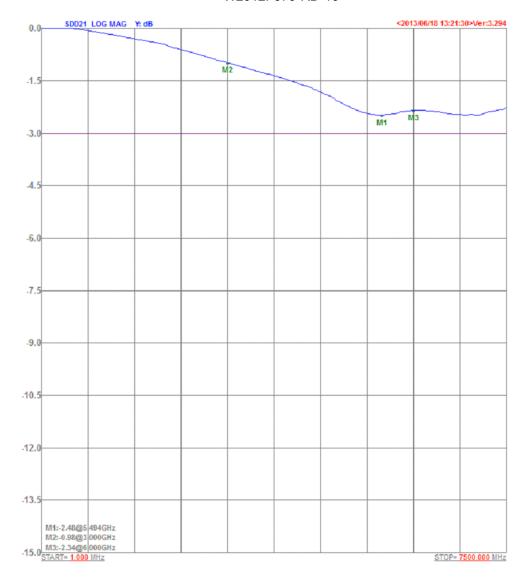


7-2. Insertion Loss Test

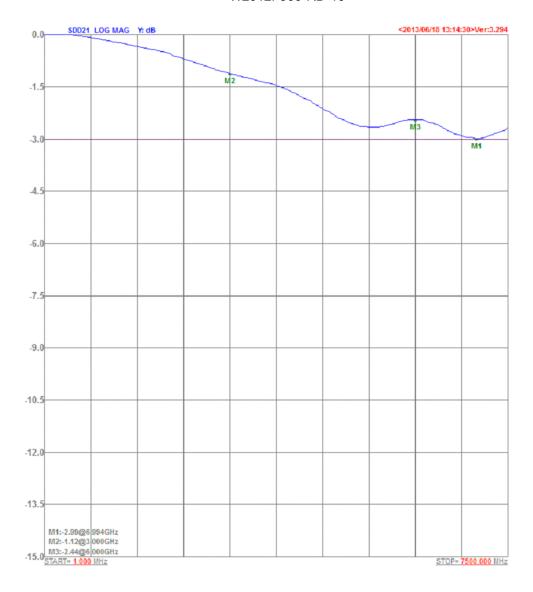
W2012F500-RD-10



W2012F670-RD-10



W2012F900-RD-10



8. Soldering Specification

Mildly activated rosin fluxes are preferred. Our terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

1-1. IR Soldering Reflow

Recommended temperature profiles for lead free re-flow soldering in Figure 1, Table 1.1 & 1.2 (J-STD-020E).

1-2. Iron Reflow

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended (Figure 2).

Note:

- (a) Preheat circuit and products to 150°C.
- (b) 355°C tip temperature (Max.)
- (c) Never contact the ceramic with the iron tip
- (d) 1.0mm tip diameter (Max.)
- (e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- (f) Limit soldering time to 4~5 sec.

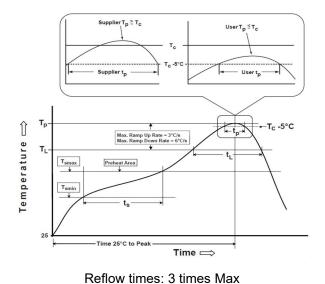
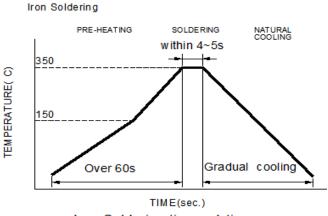


Figure 1: IR Soldering Reflow



Iron Soldering times: 1 times max.

Soldering iron method: 350±5°C Max

Figure 2: Iron soldering temperature profiles



Table (1.1) Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat	
-Temperature Min (T _{smin})	150°C
-Temperature Max (T _{smax})	200°C
-Time (t _s) from (T _{smin} to T _{smax})	60-120seconds
Ramp-up rate (T _L to T _p)	3°C /second max.
Liquids temperature (T _L)	217°C
Time (t∟) maintained above T∟	60-150 seconds
Classification temperature (Tc)	See Table (1.2)
Time (t _p) at Tc- 5°C (Tp should be equal to or less than Tc.)	*< 30 seconds
Ramp-down rate $(T_p \text{ to } T_L)$	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

Tp: maximum peak package body temperature, **Tc**: the classification temperature.

For user (customer) **Tp** should be equal to or less than **Tc**.

Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package	Volume mm ³	Volume mm ³	Volume
	Thickness	<350	350-2000	mm³ >2000
PB-Free	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
Assembly	≥2.5mm	250°C	245°C	245°C

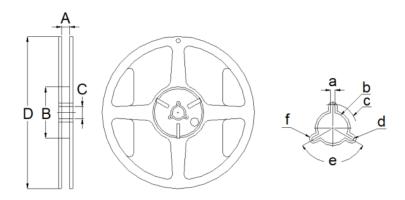
Reflow is referred to standard IPC/JEDEC J-STD-020E.

Document of Superworld

^{*}Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

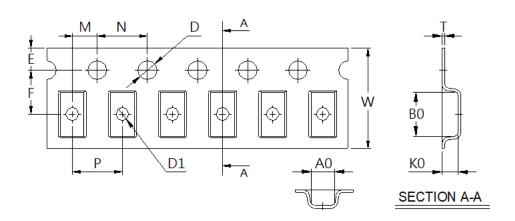
9. Packaging Information

9-1. Reel Dimension (Unit: mm)



Typo	А	В	С	D	а
Туре	9.0±0.5	60.0±2.0	13.5 Ref	178.0±2.0	2.0 Ref
7"v0mm	b	С	d	е	f
7"x8mm	13.5 Ref	R10.5	R0.5	120°	R1.9

9-2. Tape Dimension (Unit: mm)



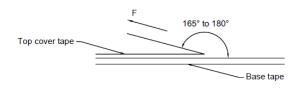
В0	A0	K0	Р	Т	E
2.25±0.10	1.50±0.10	1.35±0.10	4.00±0.10	0.22±0.05	1.75±0.10
F	М	N	D	D1	W
3.50±0.05	2.00±0.05	4.00±0.10	1.50+0.10/-0.00	1.00±0.10	8.00±0.10



9-3. Packaging Quantity (Unit: Pcs)

Chip/ Reel	2,000
Inner Box	10,000
Middle Box	50,000
Carton	100,000

9-4. Tearing Off Force



The force for tearing off cover tape is according to the follow table, in the arrow direction under the following conditions.

(Referenced ANSI/EIA-481-D-2008 of 4.11 standard)

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed (mm/min)
5~35	45~85	860~1060	300±10

Tape Size	8 mm	12 to 56 mm	72 mm or Wider
Tearing Off Force (grams)	10~100	10~130	10~150

Application Notice

1. Storage Conditions

To maintain the solderability of terminal electrodes:

- (a) Recommended products should be used within 12 months from the time of delivery.
- (b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation

- (a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- (b) Vacuum pick up is strongly recommended for individual components.
- (c) Bulk handling should ensure that abrasion and mechanical shock are minimized.

